

ABSTRACT OF THE DISCLOSURE

A method and apparatus for singulating a semiconductor substrate such as a wafer into individual components are disclosed. The peripheral edge of the substrate (termed the "edge bead ring" or "EBR") where no components are fabricated is used as a support ring in place of a conventional film frame to support the substrate. The substrate to be diced may be polymer coated or uncoated. If the EBR is of insufficient width to provide a support ring or is discontinuous, a polymer support ring may be formed about the periphery of the substrate. Adhesive-coated tape such as a UV tape is applied to the backside of the substrate and cut to the size of the substrate. The substrate is then cut to singulate components within the peripheral support ring and the singulated components removed from the tape. The remaining support ring and any defective components may be discarded.

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